

Surface Mount Schottky Barrier Rectifier
Reverse Voltage - 20 to 200 V Forward Current - 3.0A

Features

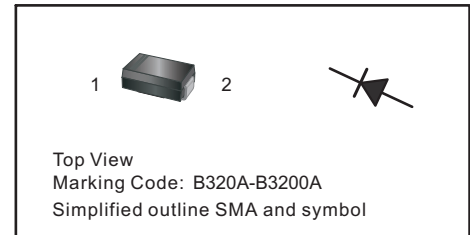
- Metal silicon junction, majority carrier conduction
- For surface mounted applications
- Low power loss, high efficiency
- High forward surge current capability
- For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications

MECHANICAL DATA

- Case: SMA
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 60mg / 0.0021oz

PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode



Absolute Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz resistive or inductive load, for capacitive load, derate by 20 %

Parameter	Symbols	B320AG	B340AG	B360AG	B380AG	B3100AG	B3120AG	B3150AG	B3200AG	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	20	40	60	80	100	120	150	200	V
Maximum RMS voltage	V_{RMS}	14	28	42	56	70	84	105	140	V
Maximum DC Blocking Voltage	V_{DC}	20	40	60	80	100	120	150	200	V
Maximum Average Forward Rectified Current	$I_{F(AV)}$	3.0								A
Peak Forward Surge Current, 8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I_{FSM}	80				70				A
Max Instantaneous Forward Voltage at 3A	V_F	0.55	0.70		0.85		0.95		V	
Maximum DC Reverse Current $T_a = 25^{\circ}C$ at Rated DC Reverse Voltage $T_a = 100^{\circ}C$	I_R	0.5 5			0.3 3				mA	
Typical Junction Capacitance ⁽¹⁾	C_j	450			400				pF	
Typical Thermal Resistance ⁽²⁾	$R_{\theta JA}$	70								°C/W
Operating Junction Temperature Range	T_j	-55 ~ +125								°C
Storage Temperature Range	T_{stg}	-55 ~ +150								°C

(1) Measured at 1 MHz and applied reverse voltage of 4 V D.C (2) P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.

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Fig.1 Forward Current Derating Curve

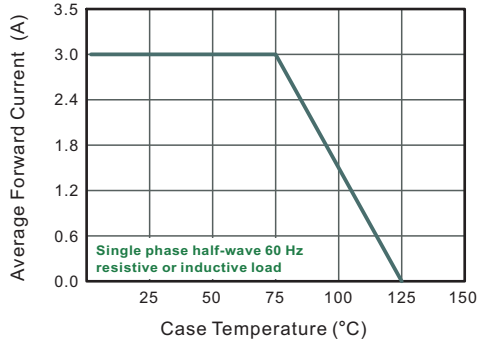


Fig.2 Typical Reverse Characteristics

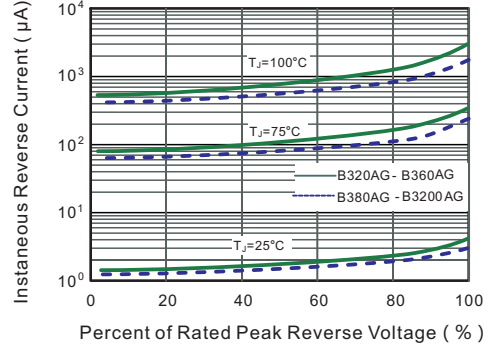


Fig.3 Typical Forward Characteristic

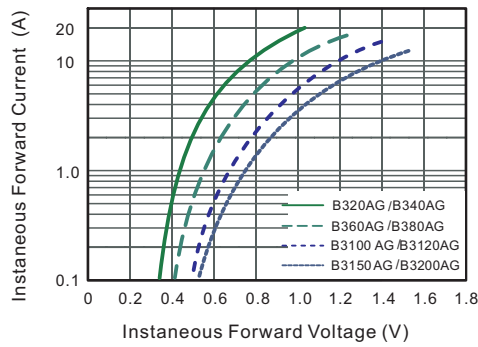


Fig.4 Typical Junction Capacitance

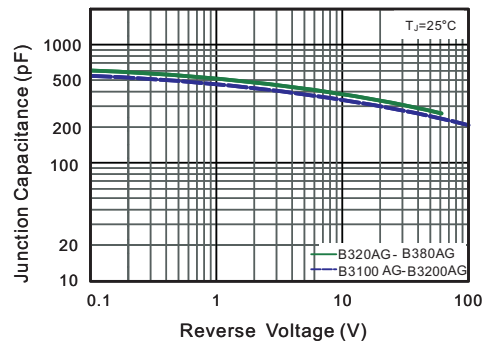


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

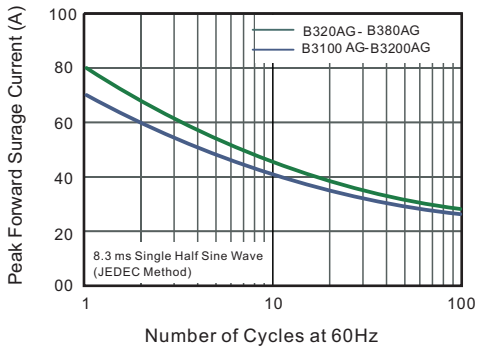
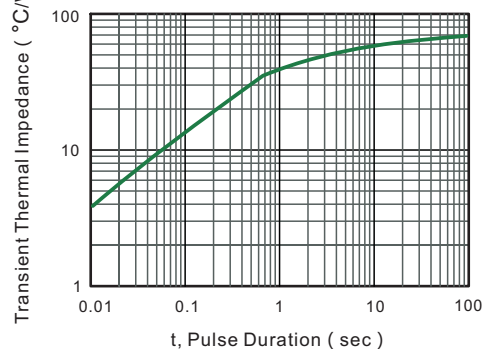


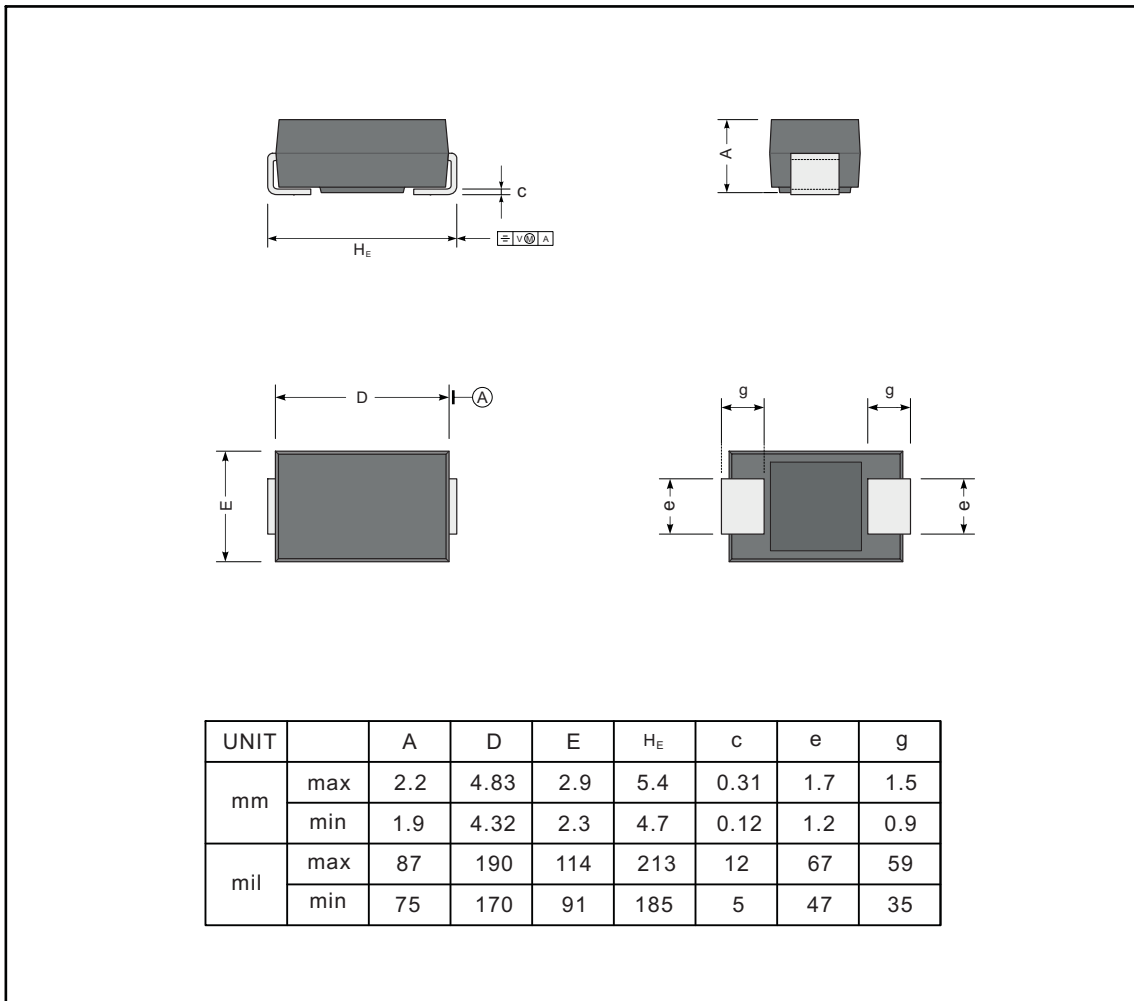
Fig.5- Typical Transient Thermal Impedance



PACKAGE OUTLINE

Plastic surface mounted package; 2 leads

SMA



The recommended mounting pad size

